



MT29C1G12MAAJVAMD-5 IT

- DATA SHEETS (1)**
- SPECS
- SIM MODELS & SOFTWARE
- ROHS CERTIFICATES
- DOCUMENTATION & SUPPORT
- PARTS WITH THE SAME DATA SHEET (4)
- WHERE TO BUY

Data Sheets (1)

Data Sheet

NAND Flash with Mobile LPDDR 130-Ball MCP Data Sheet

J4MK; MT29C1G12MAAIVAMD-5 IT, MT29C1G12MAAIYAMD-5 IT, MT29C1G12MAAJVAMD-5 IT, MT29C1G12MAAJYAMD-5 IT, MT29C1G12MAAIYAMR-5 AIT

File Type: PDF **Updated:** 10/2015

Multichip Packages
NAND LPDDR
NAND-Based MCP

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Specs

Orderable Parts for: **MT29C1G12MAAJVAMD-5 IT**

[SEE ALL NAND-BASED MCP PARTS](#)

	Status	Media	FBGA Code	SPD Data	Chipset Validation	PLP	Start Date	Alternative Part
MT29C1G12MAAJVAMD-5 IT	Production	N/A	JW805	N/A	N/A	No		N/A

Detailed Specifications

Part Status Code	Production	NAND Density	1Gb	DRAM Type	LPDDR	DRAM Density	512Mb
Bus Width	x8	Secondary Bus Width	x16	RoHS	Yes	Voltage	1.7V-1.9V
Package	VFBGA	Pin Count	130-ball	Clock Rate	200 MHz	Operating Temp	-40C to +85C

Sim Models & Software

Sim Models

IBIS

IBIS: J4MK (ZIP)

Multichip Packages
NAND LPDDR

NAND Flash + LPDDR MCP; MT29C1G12MAAIYAMR-5 AIT, MT29C1G12MAAIVAMD-5 IT, MT29C1G12MAAIYAMD-5 IT, MT29C1G12MAAJVAMD-5 IT, MT29C1G12MAAJYAMD-5 IT, MT29C1G12MAAJVAKC-5 IT

File Type: ZIP

Updated: 02/23/2015

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RoHS Certificates

RoHS Certificates

RoHS Certificate of Compliance (PDF)

MT29C1G12MAAJVAMD-5 IT

Part-specific certification of how this product meets the requirements of the current DIRECTIVE 2002/95/EC, a.k.a. Restriction of Hazardous Substances (RoHS) Directive.

File Type: (PDF)

Updated: 11/2016

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RoHS Certificates

China RoHS Certificate (PDF)

MT29C1G12MAAJVAMD-5 IT

Part-specific certification as required by China's Management Methods for Controlling Pollution by Electronic Information Products.

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Documentation & Support

[See All NAND-Based MCP Documentation](#)

Technical Notes

SEARCH (2) NAND-BASED MCP TECHNICAL NOTES

Technical Notes

TN-00-01: Moisture Sensitivity of Plastic Packages (PDF)

(TN-00-01) This technical note describes shipping procedures for preventing memory devices from absorbing moisture and recommendations for baking devices exposed to excessive moisture.

File Type: PDF

Updated: 02/14/2013

DDR SDRAM
DDR2 SDRAM
DDR3 SDRAM
DDR3L-RS
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Technical Notes

TN-10-08: Thermal Implications for LPDDR Die Stacks (PDF)

(TN-10-08) This technical note presents a case study of a handset simulation in which an LPDRAM is stacked on an application processor (PoP) and the resulting thermal-profile modeling. This note also explains how thermal detection features included in LPDDR and LPDDR2 can be used to...

File Type: PDF

Updated: 07/26/2010

Mobile Memory Solutions
Multichip Packages
NAND-Based MCP

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[SEARCH \(2\) NAND-BASED MCP TECHNICAL NOTES](#)

Customer Service Note

Customer Service Note

Customer Service Note

PoP User Guide (PDF)

(CSN-34) Provides several well-established guidelines for package-on-package (PoP) semiconductor package design and assembly, which requires unique considerations in both the up-front design and the manufacturing process.

File Type: PDF

Updated: 05/16/2016

Multichip Packages
NAND-Based MCP

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Customer Service Note

Micron Component and Module Packaging (PDF)

(CSN-16) Explanation of Micron packaging labels and procedures.

File Type: PDF

Updated: 01/08/2016

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[SEARCH \(2\) NAND-BASED MCP CUSTOMER SERVICE NOTE](#)

Parts with the same Data Sheet (4)

MT29C1G12MAAJVAMD-5 IT (Current)	MT29C1G12MAAIVAMD-5 IT	MT29C1G12MAAIYAMD-5 IT	MT29C1G12MAAJYAMD-5 IT	
Part Status Code	Production	Production	Production	Contact Factory
NAND Density	1Gb	1Gb	1Gb	1Gb
DRAM Type	LPDDR	LPDDR	LPDDR	LPDDR
DRAM Density	512Mb	512Mb	512Mb	512Mb
Bus Width	x8	x8	x8	x16
Secondary Bus Width	x16	x16	x32	x16
RoHS	Yes	Yes	Yes	Yes
Voltage	1.7V-1.9V	1.7V-1.9V	1.7V-1.9V	1.7V-1.9V
Package	VFBGA	VFBGA	VFBGA	VFBGA
Pin Count	130-ball	130-ball	130-ball	130-ball
Clock Rate	200 MHz	200 MHz	200 MHz	200 MHz
Operating Temp	-40C to +85C	-40C to +85C	-40C to +85C	-40C to +85C

Where to Buy

Orderable Parts

	Status	Media	FBGA Code	SPD Data	Chipset Validation	PLP	Start Date	Alternative Part
MT29C1G12MAAJVAMD-5 IT	Production	N/A	JW805	N/A	N/A	No		N/A

Contact Your Sales Rep

- OR - Check with Distributors

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